Neutron Radiation induced Effects in 4H-SiC p-in-n Diodes



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Irradiation + Electrical Characterization

TCAD + Simulations



Neutron Irradiation at ATI Vienna, fluences up to $1 \cdot 10^{16} n_{eq}/cm^2[6]$ • Electric rectification characteristics lost [7] • I_{leak} < 10 pA up to 1.2 kV • Flat 1/C² curve • Further studies needed to identify

and model defects



SYNOPSYS® GLOBAL TCAD SOLUTIONS



- Device simulation using TCAD, Synopsys Sentaurus and Global TCAD Solutions [8]
- GTS: Collaboration to implement 4H-SiC [9]
- Convergence and material parameters were studied

• Doping profile extracted from C-V measurements

Charge Collection Efficiency (α , p⁺, UV-TCT)









- 62.4 MeV p^+ (5 MIP eqv.) detected up to fluences of $1 \cdot 10^{15} n_{eq}/cm^2$, in reverse and forward bias
- <u>CCE still improving at high voltages</u>
- HV limited by readout electronics and detector passivation
- Highest fluences: limitations by sensor thickness and electronics



- Setup improved over previous studies [7, 10, 11]
- Up to 10% CCE at $1 \cdot 10^{16} n_{eq}/cm^2$
- <u>CCE follows</u> $\Phi_{eq}^{-0.56}$ <u>dependency</u>



Outlook

- SiC Low Gain Avalanche Diode (LGAD)
- Highly doped gain layer → Impact Ionization • Large Signals
- Better timing than Si possible [12]
- Medical Applications









• FLASH dosimetry / Microdosimetry [14]



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Wafer layout of new production

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